

REMARKS

By the present Amendment, minor revisions have been made in the specification and the extraneous colon has been deleted in claim 5. In addition, claim 1 has further been amended so that the term "polymerization unit" has been replaced with "polymer structure" consistent with the defined structural formula which makes clear an understanding of the molar percentages "x" and "y" with respect to the stated structure without altering the scope thereof. With these revisions to the claims and in light of the teachings in the specification including illustrative polymer compounds on pages 18-20, the objection and rejection based on 35 U.S.C. §112 set forth in the Official Action are believed to be fully met. The present Amendment further amends claim 1 to incorporate the substance of claim 2 and claim 2 has accordingly been canceled without prejudice or disclaimer.¹

Turning to the rejection under 35 U.S.C. §102(a) over JP 2001-131445, applicants respectfully submit that the disclosed coating film resin composition does not provide a polymer compound as defined in the claims currently under consideration. In particular, claim 1 recites a polymer compound comprising a polymer structure represented by the defined structure with a defined silane coupling group as a terminal of the polymer. The polymer structure must contain a first portion (in a molar percentage of "x") and can have a second portion (in a molar percentage of "y"). Both portions require a pendant group of $(-L^1-Y^1)$ or $(-L^2-Y^2)$. In these pendant groups, L is a direct bond or an organic connecting group as illustrated on page 10 of the specification. The group Y is independently $-N(R^7)(R^8)$, $-OH$, $-NHCOR^7$, $-COR^7$, $-CO_2M$, or $-SO_3M$, wherein R^7 and R^8 each independently

¹ Applicants also hereby affirm the election of the subject matter of Group I which originally contained claims 1, 2 and 5.

represents a hydrogen atom or an alkyl group having 1 to 8 carbon atoms and M represents a hydrogen atom, an alkali metal, an alkaline earth metal, or an onium. The defined silane coupling group includes a sulfide group connected to 1-8 methylene groups. The claimed polymer compound is well suited for use in a lithographic printing plate as defined in claim 5 and it is noted with appreciation that the Examiner has found this aspect of the invention to be allowable in the Official Action.

As noted above, JP 2001-131445 relates to a coating film resin composition and also relates to a resin molded article with a coating film that is said to have excellent anti-fogging performance. The composition comprises 100 parts by weight of a polymerizable monomer mixture composed of 10-80 wt. % of polyethylene glycol di(methacrylate), 0.1-20 wt. % of di(methacrylate), 0.1-40 wt. % hydrophilic monomer and 0.1-50 wt. % of colloidal silica whose surface has been modified with a hydrolyzate of a (meth)acrylic functional silane compound and a hydrolyzate of a hydrophilic non-(meth)acrylic functional silane compound, plus surface active agents and an initiator. The Examiner has asserted in the Action that the polyethylene (meth)acrylate meets the claimed polymerization structure.

The '445 publication does not disclose or suggest the presently claimed invention. As can be understood by the explanation provided above, the first portion (in a molar percentage of "x") and the second portion (in a molar percentage of "y") both require a pendant group of $(-L^1-Y^1)$ or $(-L^2-Y^2)$ wherein L is a direct bond or an organic connecting group and Y is independently $-N(R^7)(R^8)$, $-OH$, $-NHCOR^7$, $-COR^7$, $-CO_2M$, or $-SO_3M$. The polyethylene (meth)acrylate of the '445 publication does not meet this structure, particularly when coupled with the defined silane

coupling group. Moreover, the '445 publication has nothing to do with lithographic printing plates and given the description in paragraphs [0044] and [0047], the publication also does not appear to expressly teach the claimed molecular weight.

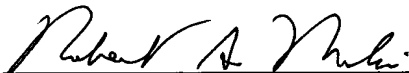
Since the claims under consideration are substantially different from the disclosed structure, applicants respectfully request reconsideration and allowance of the present application.

Should the Examiner have any questions concerning the subject application, the Examiner is invited to contact the undersigned attorney at the number provided below.

Respectfully submitted,

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